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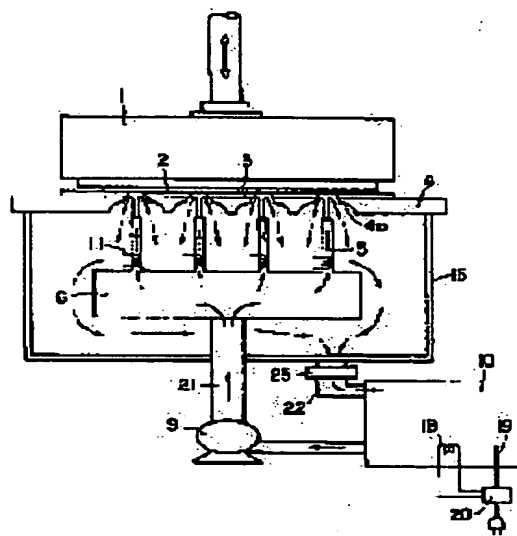
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## (54) PLATING DEVICE FOR LEAD FRAME

### (57)Abstract:

**PURPOSE:** To increase a current density and to rapidly plate a lead frame by heating a plating liquid injected from injection nozzles to this lead frame to a high temp.

**CONSTITUTION:** A lead frame 2 is held between a jig 4 for a mask having through-holes 4a and a press block 1. The plating liquid in a plating liquid tank 10 is introduced by a supply line 21 to injection nozzles 5 and is heated by the heaters 11 of the injection nozzles 5. The heated plating liquid is injected from the through-holes 4a of the jig 4 for mask to the lead frame 2. The plating liquid injected to the lead frame 2 is thereafter returned from the bottom of a sparger 15 through a return line 22 to the plating liquid tank 10.



## LEGAL STATUS

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